# NA Traceability Committee Meeting Minutes
SEMICON West 2013
Thursday, 11 July, 2013, 1:00 PM - 3:00 PM
San Francisco Marriott Marquis, San Francisco, CA

**Next Committee Meeting**
July 2014, San Francisco Marriott Marquis, CA in conjunction with SEMICON West. Check
www.semi.org/standards for the latest update.

**Attendees:**

**SEMI Staff**
Kevin Nguyen – SEMI NA

**Co-chair – Win Baylies (BayTech Group)**

**Table 1 – Meeting Attendees**

| Last Name | First Name | Company |
|-----------|------------|---------|
| Baylies | Win | BayTech Group |
| Brown | David | Intel |
| Obeng | Yaw | NIST |
| Trego | James | James Trego |

**Table 2 – Task Force Change**

| Group | Changes |
|-------|---------|
| None | |

**Table 3 – Ballot Summary**

| Document # | Document Title | Committee Action |
|------------|----------------|------------------|
| 5581 | Revision of SEMI T3-0302 (Reapproved 1108), Specification for Wafer Box Labels | Passed as balloted |
| 5582 | Reapproval of SEMI T4-0301 (Reapproved 0307), Specification for 150 mm and 200 mm Pod Identification Dimensions | Passed as balloted |
| 5487A | New Standard: Specification for Basic Protocols to Support the Interoperation of Traceability Systems Necessary for Managing Product Identity throughout the Life Cycle of Objects Using Digital Signatures and Time Stamps | Failed and reballot |

**Table 4 – Authorized Ballots**

| # | When | SC/TF/WG | Details |
|---|------|----------|---------|
| 5612 | Cycle 1-2014 | NA Traceability Committee | Reapproval of SEMI T7-0303 (Reapproved 0709), Specification for Back Surface Marking of Double-Side Polished Wafers with a Two-Dimensional Matrix Code Symbol |
| 5613 | Cycle 1-2014 | NA Traceability Committee | Reapproval of SEMI T11-0703 (Reapproved 0709), Specification for Marking of Hard Surface Reticle Substrates |
| 5614 | Cycle 1-2014 | NA Traceability Committee | Revision of SEMI T3, Specification for Wafer Box Labels (Re: to extend application to other symbologies and Near-Field Communication) |

**Table 5 – Authorized Activities**
Listing of all new TFOFs, SNARFs, and other activities approved by the committee.

| # | Type | SC/TF/WG | Details |
|---|------|----------|---------|
| 5612 | SNARF | NA Traceability Committee | Reapproval of SEMI T7-0303 (Reapproved 0709), Specification for Back Surface Marking of Double-Side Polished Wafers with a Two-Dimensional Matrix Code Symbol |
| 5613 | SNARF | NA Traceability Committee | Reapproval of SEMI T11-0703 (Reapproved 0709), Specification for Marking of Hard Surface Reticle Substrates |
| 5614 | SNARF | NA Traceability Committee | Revision of SEMI T3, Specification for Wafer Box Labels (Re:to extend application to other symbologies and Near-Field Communication) |

**Note:** SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF


**Table 6 – Previous Meeting Actions Items**
None

**Table 7 – New Actions Items**

| Item # | Assigned to | Details |
|--------|-------------|---------|
| 0713-1 | Dave Brown (Intel), Win Baylies (BayTech) | To contact Rob van Wezel (Salland) for revision of SEMI T3 Specification for Wafer Box Labels (Extend application to other symbologies and Near-Field Communication) |
| 0713-2 | Kevin Nguyen (SEMI Staff) | To review the Traceability Committee member list and remove inactive members |

## 1.0 Call to Order
Win Baylies called the meeting to order and welcomed everyone who attended. A round of self introduction was made. All SEMI standards meetings are subjected to SEMI Anti-Trust Reminder and Guidelines concerning Patentable Technology. SEMI Regulations now require all attendees to be members of SEMI standards. If not a member, please enroll at www.semi.org/standardsmembership. Agenda was reviewed and approved as written.

## 2.0 Review and Approval of the Meeting Minutes from the NA Spring, April 2, 2013, Meeting
Minutes were reviewed. No change was made.
**Motion:** To accept the minutes as corrected
**By / 2ⁿᵈ:** Jim Trego (Consultant)/Yaw Obeng (NIST)
**Discussion:** None
**Vote:** Unanimous. Motion passed

Attachment – 1, NATraceabilityMinutes20130404

## 3.0 Staff Report
Staff report was presented by Kevin Nguyen. Highlights.

- 2013 & 2014 Event

| Event Name | Event Details |
|------------|---------------|
| **SOLARCON India** | **August 1-3, 2013** **Bangalore** |
| **SEMICON Taiwan** **LED Taiwan** | **September 4-6, 2013** **Taipei** |

| Event Name | Event Details |
|---|---|
| **SEMICON Europa** | **October 8-10, 2013**<br>**Dresden, Germany** |
| **PE2013 – Plastic Electronics Exhibition and Conference** | **October 8-10, 2013**<br>**Dresden, Germany** |
| **PV Taiwan** | **October 30 – November 1, 2013**<br>**Taipei** |
| **SEMICON Japan** | **December 4-6, 2013**<br>**Chiba** |
| **SEMICON Korea** | **February 12-14, 2014**<br>**Seoul** |
| **LED Korea** | **February 12-14, 2014**<br>**Seoul** |

- Silicon Wafers – Future Standardization to Enable the Transition (2:30 PM to 6:00 PM)
  - Agenda:
    - Towards 450 mm Silicon Wafers, Mike Goldstein (Intel)
    - Notchless Wafer, Pinyen Lin (G450C)
    - New Edge Exclusion Proposal, Kwangwook Lee (G450C)
    - Wafer Geometry for Advanced Nodes, Gerd Pfeiffer (IBM)
    - Challenges during 450 mm Silicon Processing, Hisashi Furuya (SUMCO)
    - 450 mm Facilities Planning, Allen Ware (F450C)
    - G450C Component Lift Program Update, Les Marshall (G450C)
  - Proceedings are available at https://sites.google.com/a/semi.org/siwaferfuturestandardstransition/

- NA Standards Fall 2013 Meetings
  - o October 28-31
  - o SEMI Headquarters in San Jose, California
  - o Inviting local companies willing and able to host some of the meetings to maintain one-week format.
- Technical Ballot Critical Dates
  - o Cycle 5, 2013
    - Ballot Submission Date: July 18
    - Voting Period Starts: July 29
    - Voting Period Ends: August 29
  - o Cycle 6, 2013
    - Ballot Submission Date: August 15
    - Voting Period Starts: August 29
    - Voting Period Ends: September 30
- June 2013 Cycle Publication Cycle
  - o New Standards: 10
  - o Revised Standards: 2
  - o Reapproved Standards: 4
  - o Withdrawn Standards: 0
- Total SEMI Standards in portfolio: 887
  - o Includes 94 Inactive Standards

Attachment – 2, SEMI Staff Report (West 2013)

**4.0    Liaison Report**

### 4.1  Japan Committee

Report was presented by Kevin. Highlights are as follows:
- Last meeting
  - April 12, 2013
  - SEMI Japan, Tokyo, Japan
- Next meeting
  - August 6, 2013
  - SEMI Japan, Tokyo, Japan
- Upcoming Ballot
  - Doc. 5594A, New Specification for Basic Protocols to Support the Interoperation of Traceability Systems Necessary for Managing Product Identity throughout the Life Cycle of Objects Using Digital Signatures and Time Stamps
  - Will be adjudicated at SEMICON West 2013
- New SNARFs & TFOFs
  - Doc. 5594, New Standard: Guide for Smart Label for PV Traceability
- Japan PV Traceability TF
  - Co-leaders
    - Yoichi Iga (Renesas Electronics)
    - Hirokazu Tsunobuchi (KEYENCE)
  - Charter
    - The objective is to define and elaborate several standards to unify PV traceability from the sliced wafer to the end of PV cell life－cycle.
  - Scope
    - The activities of the task force will result in the development of several industry standards where equipment suppliers, cell manufacturers, PV module manufacturers, PV users and other involved parties can find conformity, in any technical field of PV traceability. Initial work will focus on
      - Marking of ID to identify a product
      - Means to identify as a right product
      - Security countermeasure to realize other Traceability depending on need
      - Anti-Counterfeiting
    - Activity
      - Doc. 5594, New Standard: Guide for Smart Label for PV Traceability

Attachment – 3, JA_Trace_NA_SW_R0.1

**5.0    Ballots Review**
- 5.1    Document 5581, Revision of SEMI T3-0302 (Reapproved 1108), Specification for Wafer Box Labels
  - 5.1.1    Document passed technical review as balloted and was forwarded to the ISC Audits and Reviews Subcommittee for procedural review.
    - 5.1.1.1    A comment was submitted by Rob van Wezel (Salland) by requesting QR codes to be added.  A SNARF will be submitted for line item change to extend application to other symbologies and Near-Field Communication. Rob will be requested to participate in this revision. Action Item 1 – Dave and Win to contact Rob for feedback on revision of SEMI T3.
    - 5.1.1.2    See attachment below for details of ballot adjudication.

Attachment – 4, 5581ProceduralReview

5.2     Document 5582, Reapproval of SEMI T4-0301 (Reapproved 0307), Specification for 150 mm and 200 mm Pod Identification Dimensions

     5.2.1     Document passed technical review as balloted and was forwarded to the ISC Audits and Reviews Subcommittee for procedural review.  See attachment below for detail of ballot adjudication.

     Attachment – 5, 5582ProceduralReview

5.3     Document 5487A, New Standards: Specification for Basic Protocols to Support the Interoperation of Traceability Systems Necessary for Managing Product Identity throughout the Life Cycle of Objects Using Digital Signatures and Time Stamps

     5.3.1     Document failed technical review and was sent back to the task force for rework and reballot.  See attachment below for detail of ballot adjudication.

     Attachment – 6, 5487AFailed

## 6.0     Subcommittee & Task Force Reports

### 6.1   ISO TC247, WG3

- Dave Brown, chairman of TC247, reported ISO has an ongoing ballot, 2 month away from closing on a 5 months ballot cycle.  The results will be available by SEMICON Japan later this year.  So far, there is no comment yet.
- Also, a security management system ballot fails to achieve consensus.  Britain and Germany did not submit their votes.  Results are pending.
- Finally, a security forum is being planned in October.  It was reported there is a proposal to impose on traceability supply chain security measure, which may impact several activities.
- For more information, contact Dave at david.a.brown@intel.com

## 7.0     Old Business
None

## 8.0     New Business

### 8.1     5 Year Review Standards
Kevin reported the following standards are due for 5 year review as required by the SEMI Regulations.
- SEMI T7-0303 (Reapproved 0709) - Specification for Back Surface Marking of Double-Side Polished Wafers with a Two-Dimensional Matrix Code Symbol
- SEMI T11-0703 (Reapproved 0709) - Specification for Marking of Hard Surface Reticle Substrates

**Motion:**  To send SEMI T7 and T11 for reapproval ballot for review in San Francisco meeting in 2014.
**By / 2ⁿᵈ:** Dave Brown (INTEL)/Yaw Obeng (NIST)
**Discussion:** These standards were reviewed.  The committee believes these standards are up to date, thus no changes are needed.  Ballots should be issued for reapproval.
**Vote:**  Unanimous. Motion passed

### 8.2     SNARF for Revision to SEMI T3 Specification for Wafer Box Labels
Revision to T3 is needed to address a comment submitted by Rob van Wezel (Salland), as discussed in section 5.1. This revision is to extend application to other symbologies and Near-Field Communication

**Motion:**  To approve T3 Revision SNARF
**By / 2ⁿᵈ:** Dave Brown (INTEL)/Yaw Obeng (NIST)
**Discussion:** Dave Brown and Win Baylies will attempt to contact Rob for help in revision.
**Vote:**  Unanimous. Motion passed
Attachment – 7, SNARF T3 Modification 130711

**8.3** Prior to the meeting, Iga-san requested the following items to be added on the agenda, but he was not available to present.

- Doc. 5487A Result of Cycle 4
  - As reviewed in section 5.3, this document failed committee review. It was recommended to send back for a major rework. The scope of this document is way beyond the scope of the Traceability committee's charter.
- Iida san's new SNARF introduction
  - The committee also reviewed SEMI Draft Document 5594, NEW STANDARD: GUIDE FOR SMART LABEL FOR PV TRACEABILITY. The general consensus was that this document is also way out of the scope of the Traceability committee. As written, the document is extremely complicate and it appears to be written for the whole supply system, which requires more than just one single document.

  Attachment – 8, SEMI 5594_YellowBallot_20130708

- TRC auditing committee deal with the scope issue
  - After reviewing the proposed charter, the NA Traceability committee does not support this proposal. Especially the charter was expanded to cover the whole supply chain, life cycle and aftermarket. Again, this does not belong in SEMI.

  Attachment – 9, CHANGE IGA Traceability Committee CHARTER   SCOPE

**8.4 Review of SEMI Traceability committee member list**
Dave Brown pointed out the decline in attendance. The Traceability committee member's list appears much more than those who have been attending and voting in the meeting. Thus, the list may not be up to date. It was requested to review the Traceability committee members. A significant number of member may have been inactive. Action Item 2 – Kevin to review the committee members list and remove those who are inactive.

**9.0    Next Meeting**
The next meeting of the NA Traceability committee is tentatively scheduled for July 2014 in San Francisco, CA in conjunction with SEMICON West 2014. Check www.semi.org/standards for the latest update.

**10.0   Action Item Review**

See table 7 above.

**11.0   Adjourn**
Adjournment of the meeting was held at 3:00 PM

These minutes are respectfully submitted by:

Kevin Nguyen,
SEMI NA Standards Committee Manager
Phone: 408-943-7997
Email: knguyen@semi.org

Approved by:
Yaw Obeng (NIST) – Co-chair
Win Baylies (BayTech Group) – Co-chair

**Table 7 – Index of Attachment Summary**

| # | Title |
|---|---|
| 1 | NATraceabilityMinutes20130404 |
| 2 | SEMI Staff Report (West 2013) |
| 3 | JA_Trace_NA_SW_R0.1 |
| 4 | 5581ProceduralReview |
| 5 | 5582ProceduralReview |
| 6 | 5487AFailed |
| 7 | SNARF T3 Modification 130711 |
| 8 | SEMI 5594_YellowBallot_20130708 |
| 9 | CHANGE IGA Traceability Committee CHARTER    SCOPE |

#1 Due to file size and delivery issues, attachments must be downloaded separately.  A .zip file containing all attachments for these minutes is available at www.semi.org.  For additional information or to obtain individual attachments, please contact Kevin Nguyen at the contact information above